

**Code**                    **REE**  
**Company name**    Refrigeration Electrical Engineering Corporation  
**Date**                    03/29/2024  
**Subject**                Report on the use of bond capital

**Content:**

Refrigeration Electrical Engineering Corporation (REE) announces the use of bond capital as follows:

1. Purpose of capital use according to the issuance plan:

Based on the bond issuance plan approved by the Board resolution dated January 22, 2019:

- Total mobilized capital from the bond issuance (at par value) and the issue volume by each bond code:

No.	Bond code	Volume (bond)
1	REEH1929001	2,318 bonds

- Purpose for capital use: to develop and pay the real estate projects.

2. Progress of capital use and disbursement:

2.1 For the purpose of capital use to invest in the project and capital restructuring:

- To invest in the real estate projects: 1,210,107,840,139 dongs (time: from March 01, 2019 to December 31, 2023)

2.2 For the purpose of capital use to raise working capital: none

2.3 For the purpose of using capital from the green bond issuance in the local market: none.